

# TLC696x0 Scan MOSFET Controller for TLC696x2/4/8

## 1 Features

- Operating voltage  $V_{CC}$  range: 3 V to 5.5 V
- Flexible P-MOSFET driving options:
  - Maximum driving current / sustaining voltage:
    - 30 mA / 20 V: TLC69600
    - 60 mA / 20 V: TLC69610
    - 30 mA / 50 V: TLC69650
    - 60 mA / 50 V: TLC69660
  - Global 8-bit Maximum Current (MC) setting
  - Individual 8-bit Channel Current (CC) setting
- High speed daisy chain interface:
  - I/O voltage compatible with: 1.8 V / 3.3 V
  - Data transfer rate: up to 20 MHz
- EMI enhancement:
  - Programmable interface driving capability
- Display quality improvement:
  - Minimum brightness update latency
  - Programmable black insertion
  - Variable refresh rate (VRR) without flickering
- Diagnostics:
  - Device thermal shutdown detection
  - Report interface option:
    - UART and interrupt pin (INT)
    - Two-wire output: CLK\_O and SOUT

## 2 Applications

- LCD local dimming backlight:
  - TV
  - Monitor
  - Notebook
  - Tablet

## 3 Description

TLC696x0 is a scan MOSFET controller compatible with current-sink driver TLC696x2/4/8 to achieve 2/4/8 time-multiplexing control. Each device integrates with 16 constant current sinks for up to 8 scan MOSFETs control. The device equips with ghost-cancellation function to eliminate upside ghosting.

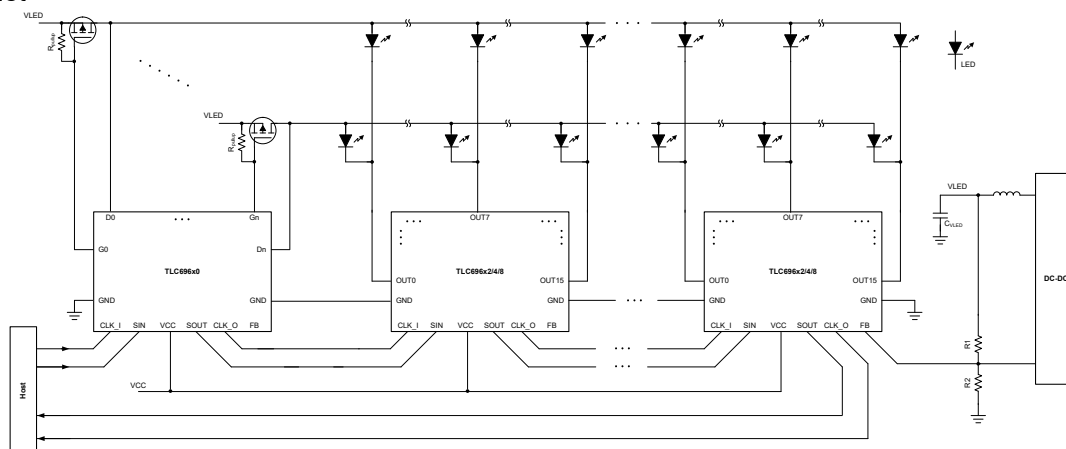
To optimize system efficiency, the device equips with adaptive headroom voltage control scheme to directly control DC/DC. Only the FB pin from last device in serial chain should be connected to DC/DC to achieve simplified system layout. The device also integrates minimum brightness update latency, black insertion and VRR features to improve display quality.

TLC696x0 has three error flags: LED open detection (LOD), LED short detection (LSD) and thermal shutdown detection (TSD) for diagnostic. The device implements two options for readback including UART/INT and SOUT/CLK\_O which is programmable by register.

### Device Information

PART NUMBER	PACKAGE <sup>(1)</sup>	BODY SIZE (NOM)
TLC696x0	DSBGA (24)	1.58 mm × 2.43 mm
	WQFN (24)	4 mm × 4 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



**Simplified Schematic**



## Table of Contents

<b>1 Features</b> .....	<b>1</b>	5.2 Support Resources.....	<b>3</b>
<b>2 Applications</b> .....	<b>1</b>	5.3 Trademarks.....	<b>3</b>
<b>3 Description</b> .....	<b>1</b>	5.4 Electrostatic Discharge Caution.....	<b>3</b>
<b>4 Revision History</b> .....	<b>2</b>	5.5 Glossary.....	<b>3</b>
<b>5 Device and Documentation Support</b> .....	<b>3</b>	<b>6 Mechanical, Packaging, and Orderable Information</b> ....	<b>4</b>
5.1 Receiving Notification of Documentation Updates.....	<b>3</b>		

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
April 2023	*	Initial Release

## 5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 5.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 5.5 Glossary

[TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.

## 6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC69600RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69600	<a href="#">Samples</a>
TLC69600YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69600	<a href="#">Samples</a>
TLC69610RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69610	<a href="#">Samples</a>
TLC69650RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69650	<a href="#">Samples</a>
TLC69660RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69660	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

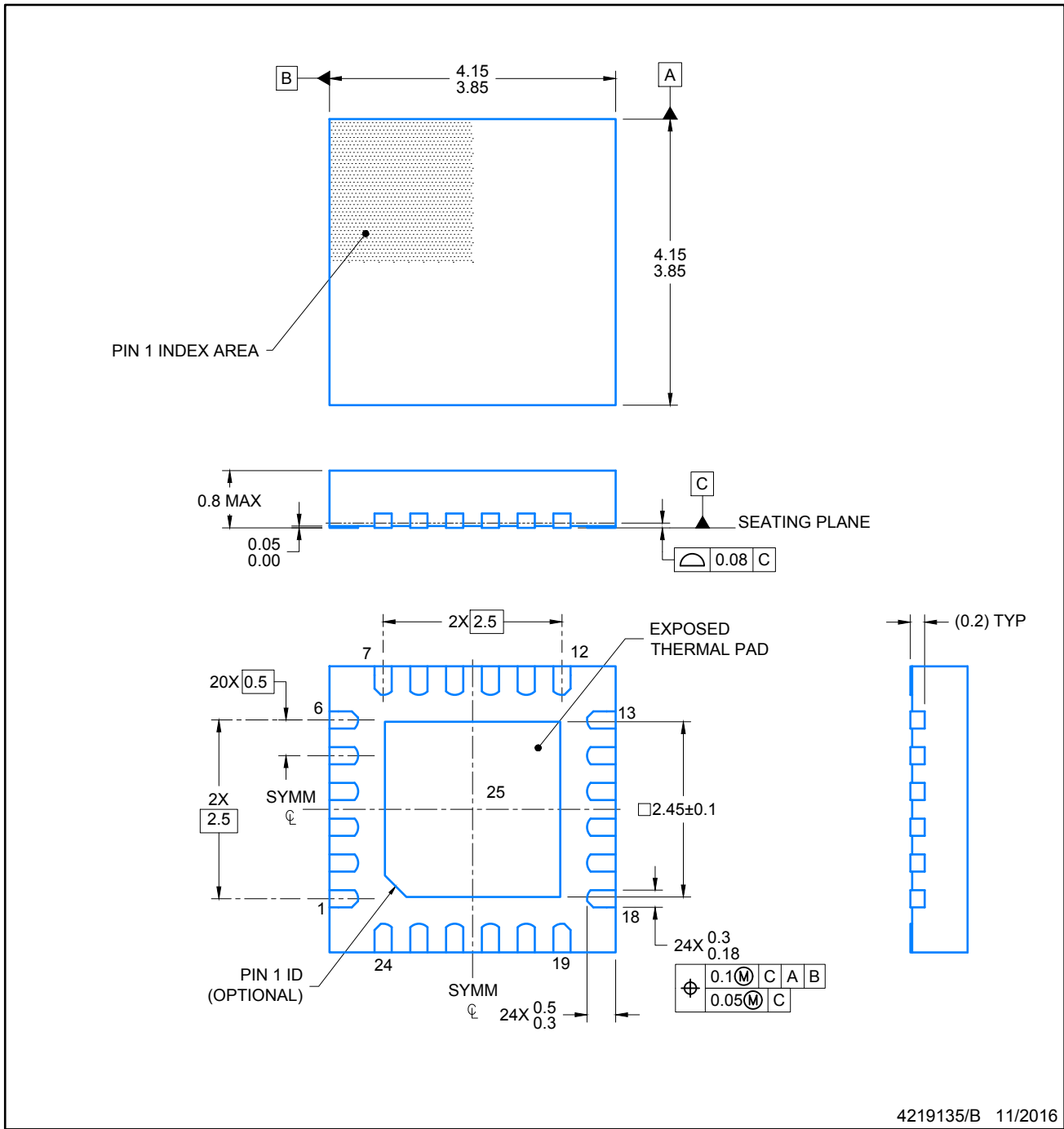
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

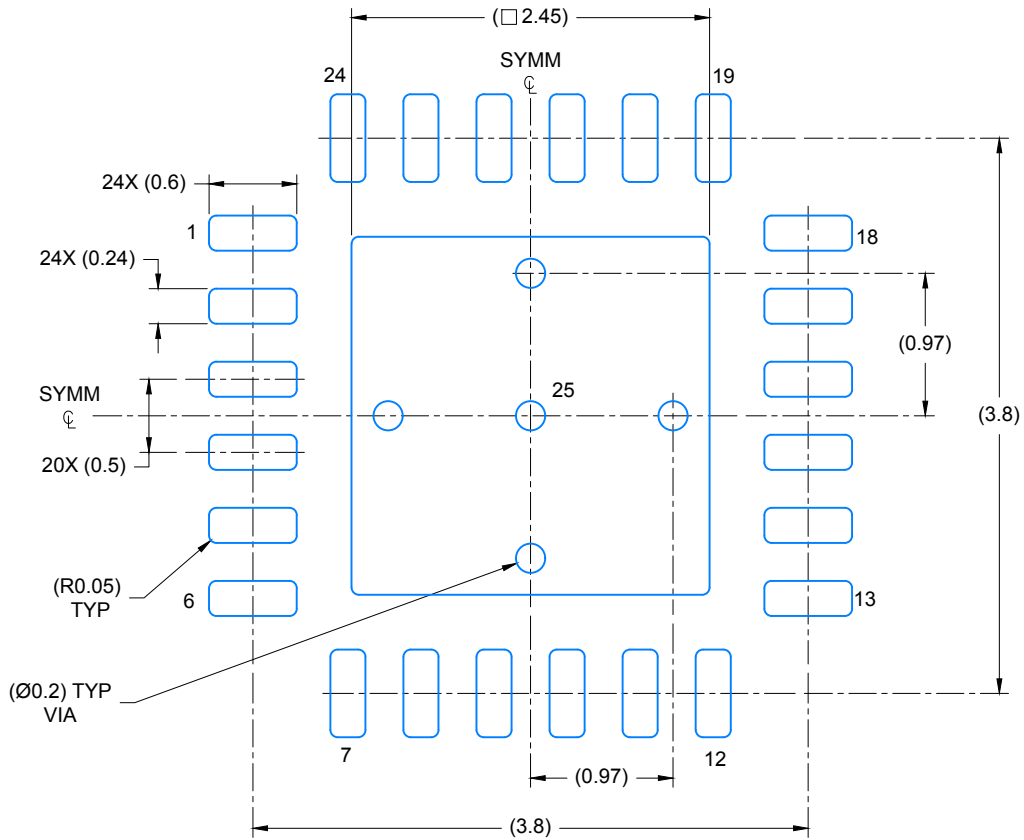
**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

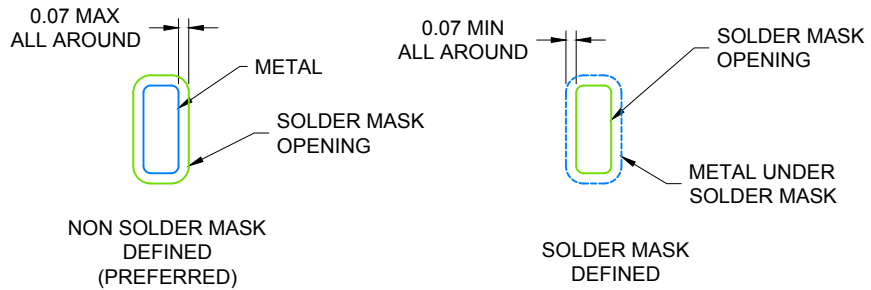


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE  
SCALE: 20X



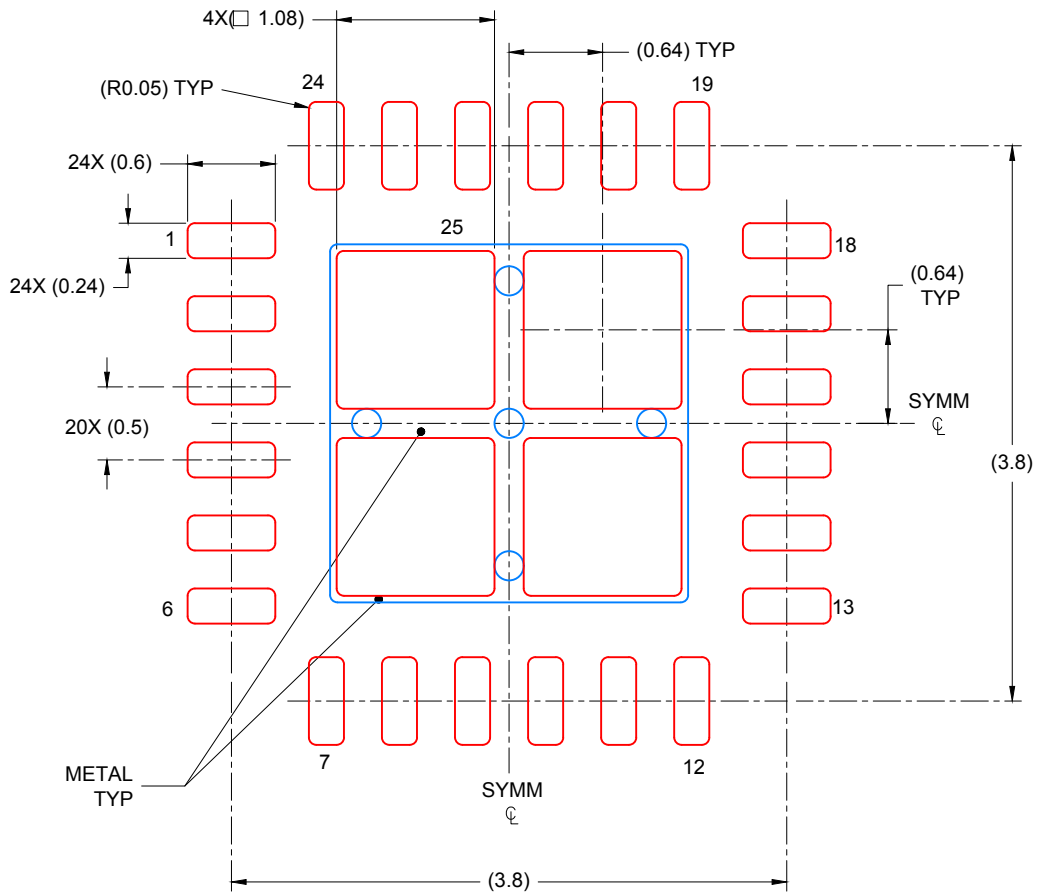
SOLDER MASK DETAILS

4219135/B 11/2016

NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sl原因271](http://www.ti.com/lit/sl原因271)).





SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:  
 78% PRINTED COVERAGE BY AREA UNDER PACKAGE  
 SCALE: 20X

4219135/B 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2023, Texas Instruments Incorporated